216419US

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

SHUNICHI IGARASHI

SERIAL NO: NEW U.S. PCT APPLN.

(Based on PCT/JP00/09265)

: ATTN: APPLICATION BRANCH

FILED: HEREWITH

FOR: METHOD, MATERIAL, AND

CONFIGURATION FOR

REINFORCING A STRUCTURE

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Prior to a first examination on the merits, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend the claims as shown in the marked-up copy attached to read as follows:

- 5. (Amended) A method for reinforcing a structure as described in Claim 1, wherein an adhesive layer is formed on at least one side of the high-ductility material, and the high-ductility material is affixed to the member via the adhesive layer.
- 6. (Amended) A method for reinforcing a structure as described in Claim 3, wherein the high-ductility material is wound on the member such that the overlap portions are bonded together and/or such that the high-ductility material is bonded to a surface of the member at at least a single zonal region extending along a length direction of the member.

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